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Expedited Procedure  
Group No. 1753

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicants: HABA et al.  
Application No.: 09/888,642  
Filed: June 26, 2001  
For: ELECTRIC COPPER PLATING LIQUID AND PROCESS FOR  
MANUFACTURING SEMICONDUCTOR INTEGRATED  
CIRCUIT DEVICE USING SAME  
Art Unit: 1753  
Examiner: E. Wong

**AMENDMENT AFTER FINAL REJECTION**

Mail Stop AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

June 25, 2004

Sir:

In response to the Office Action mailed March 25, 2004, please amend the  
above-identified application as listed in the following, and as set forth on the  
following pages:

Amendments to the Claims; and

Remarks are included following the amendments.